

March 19, 2014

Brought into session at 9:06am.

Introductions made

David Abramson volunteered to be recording secretary for this meeting

David Abramson answered call for press with notice about his blog.

Dave Dwelley made a request for an editor.

Usual introductory presentation given.

Dave Dwelley read the patent slides (slides 1-4) and made the call for essential patents.

There was discussion about the process used for patent claims and LOA notices.

Geoff Thompson answered the call for potentially essential patents and informed the chair of the identity of the holder of the patent that may be essential.

Yair Darshan announced that MicroSemi has submitted an LOA for 802.3bu.

Dave Dwelley gave the 1000Base-T1 Liaison Report: http://www.ieee802.org/3/bu/public/mar14/dwelley_3bu_1_0314.pdf

Jeff Heath gave the Power Ad Hoc Report: http://www.ieee802.org/3/bu/public/mar14/heath_3bu_1_0314.pdf

Motion to approve the minutes from Jan. 2014 approved by acclimation with no opposition. Moved by Matthias Wendt, seconded by Faisal Ahmad.

Meeting recessed at 10:11am for break and ad hoc meetings.

Meeting called back into session at 11:31am.

Dave Dwelley conducted two straw polls:

1. Will you be attending the Interim Meeting in Norfolk VA in May 2014?

Yes: 6, Maybe: 5, No: 3

2. Will you be generating a presentation for the Norfolk Interim Meeting?

Yes: 2, Maybe: 0, No: everyone else

Group chartered Dave Dwelley and Yair Darshan to draft question regarding noise levels and data integrity to bring to 802.bp group. Confirmed by voice acclimation without opposition.

Adjourned at 11:43. Motion moved by Chad Jones, seconded by Jeff Heath.

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